

REMARKS

Claim 2 and new claims 15-27 are pending in this application.

The support for the claim amendments and new claims are as follows: Claim 2 (p.16, lines 2-7); Claim 15-23 (p.15, lines 14-25); Claim 24 (FIG. 2C); Claim 25 (p.16, lines 2-7); Claim 26 (p. 31, lines 10-12) and Claim 27 (p.57, lines 12-18).

A substitute abstract is provided as recommended by the Examiner.

Claim 2 is rejected under 35 USC 102(e) as being anticipated by **Ohsawa '436**.

In response to the Examiners helpful Response to Arguments in the Office Action dated January 29, 2003; the applicants have amended claim 2 to more clearly recite the features upon which the applicants rely for patentability over **Ohsawa '436**. Specifically, claim 2 now clearly recites, forming an insulating film on a metal base having openings on the metal base at positions corresponding to metal bumps to be formed later.

In short the amendment to independent claim 2 makes the presence of the insulating film clear. **Ohsawa '436** does not at all disclose an insulating film, shown as "insulating resin layer-1" in the figure submitted with the last response on November 27, 2002.

As apparent from claims 1 and 5 and the figures of **Ohsawa '436**, the insulating layer is not applied until late, whereas in the claimed invention, the insulating layer is formed on the metal base. Without the disclosure of forming an insulating film on a metal base having openings on the metal base at positions corresponding to metal bumps to be formed later, **Ohsawa '436** cannot possibly

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anticipate.

It is requested that amended claim 2 and the new claims be reconsidered in light of the amendments.

In view of the aforementioned amendments and accompanying remarks, claims 2 and 15-27, as amended, are believed to be in condition for allowance, which action, at an early date, is requested.

If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicants undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

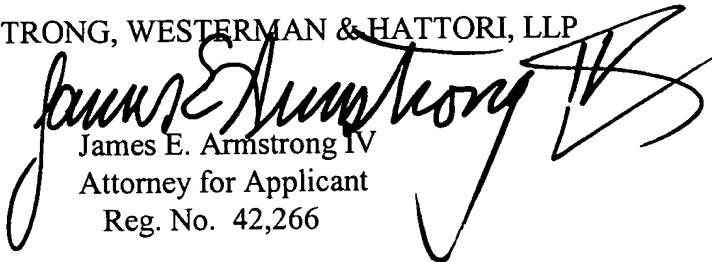
Attached hereto is a marked-up version of the changes made to the claim 2 by the current amendment. The attached page is captioned "Version with markings to show changes made."

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In the event that this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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Enclosures: Version with markings to show changes made

Q:\FLOATERS\JAMIE\99\991450\AMENDMENT

VERSION WITH MARKINGS TO SHOW CHANGES MADE 09/466,895

IN THE CLAIMS:

Please amend Claim 2, as follows:

2. (Amended) A method for fabricating a wiring substrate comprising the steps of:

forming an insulating film on a metal base having openings on the metal base at positions
corresponding to metal bumps to be formed later;

forming at least one layer of wiring on the [a] base made of a metal through the [an]
insulating film, the layer of wiring having a wiring film formed thereon by electroplating; and
selectively etching the base.

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